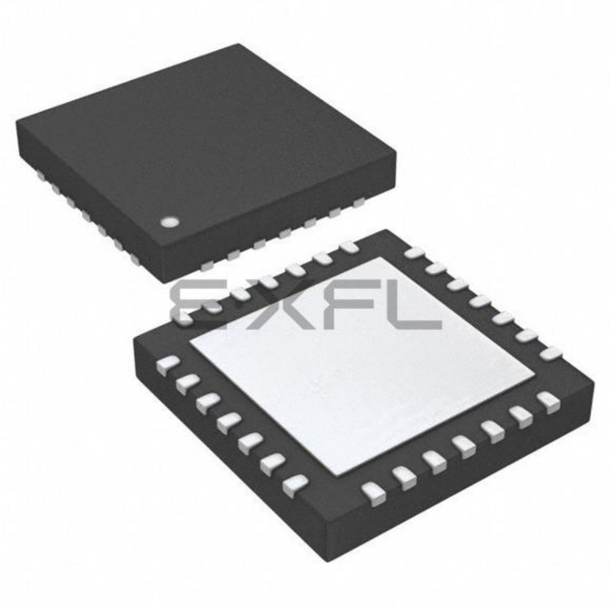
Microchip Technology - PIC16F1826-I/ML Datasheet



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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	32MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	16
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16f1826-i-ml

3.2.2 SPECIAL FUNCTION REGISTER

The Special Function Registers are registers used by the application to control the desired operation of peripheral functions in the device. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses x0Ch/x8Ch through x1Fh/x9Fh). The registers associated with the operation of the peripherals are described in the appropriate peripheral chapter of this data sheet.

3.2.3 GENERAL PURPOSE RAM

There are up to 80 bytes of GPR in each data memory bank. The Special Function Registers occupy the 20 bytes after the core registers of every data memory bank (addresses x0Ch/x8Ch through x1Fh/x9Fh).

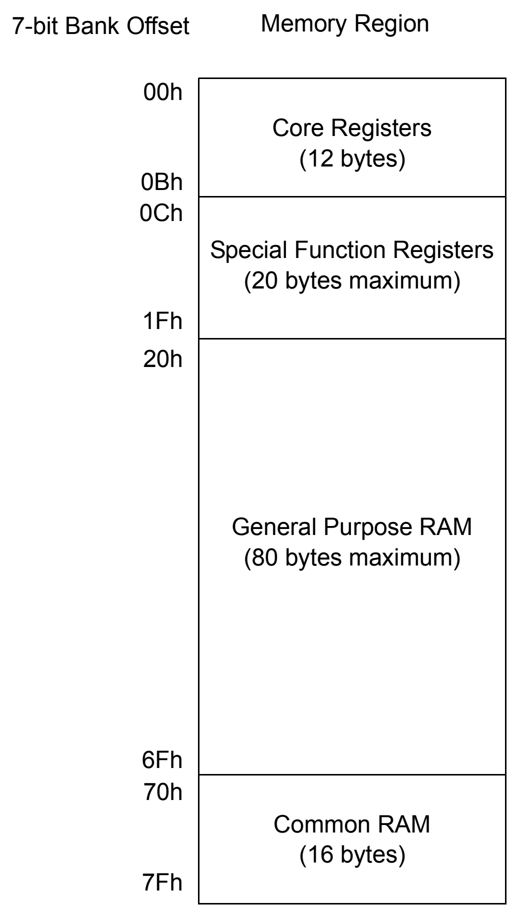
3.2.3.1 Linear Access to GPR

The general purpose RAM can be accessed in a non-banked method via the FSRs. This can simplify access to large memory structures. See **Section 3.5.2 “Linear Data Memory”** for more information.

3.2.4 COMMON RAM

There are 16 bytes of common RAM accessible from all banks.

FIGURE 3-3: BANKED MEMORY PARTITIONING



3.2.5 DEVICE MEMORY MAPS

The memory maps for the device family are as shown in Table 3-3 and Table 3-4.

5.2.2.6 32 MHz Internal Oscillator Frequency Selection

The Internal Oscillator Block can be used with the 4X PLL associated with the External Oscillator Block to produce a 32 MHz internal system clock source. The following settings are required to use the 32 MHz internal clock source:

- The FOSC bits in Configuration Word 1 must be set to use the INTOSC source as the device system clock (FOSC<2:0> = `100`).
- The SCS bits in the OSCCON register must be cleared to use the clock determined by FOSC<2:0> in Configuration Word 1 (SCS<1:0> = `00`).
- The IRCF bits in the OSCCON register must be set to the 8 MHz HFINTOSC set to use (IRCF<3:0> = `1110`).
- The SPLLEN bit in the OSCCON register must be set to enable the 4xPLL, or the PLLEN bit of the Configuration Word 2 must be programmed to a ‘`1`’.

Note: When using the PLLEN bit of the Configuration Word 2, the 4xPLL cannot be disabled by software and the 8 MHz HFINTOSC option will no longer be available.

The 4xPLL is not available for use with the internal oscillator when the SCS bits of the OSCCON register are set to ‘`1x`’. The SCS bits must be set to ‘`00`’ to use the 4xPLL with the internal oscillator.

5.2.2.7 Internal Oscillator Clock Switch Timing

When switching between the HFINTOSC, MFINTOSC and the LFINTOSC, the new oscillator may already be shut down to save power (see Figure 5-7). If this is the case, there is a delay after the IRCF<3:0> bits of the OSCCON register are modified before the frequency selection takes place. The OSCSTAT register will reflect the current active status of the HFINTOSC, MFINTOSC and LFINTOSC oscillators. The sequence of a frequency selection is as follows:

1. IRCF<3:0> bits of the OSCCON register are modified.
2. If the new clock is shut down, a clock start-up delay is started.
3. Clock switch circuitry waits for a falling edge of the current clock.
4. The current clock is held low and the clock switch circuitry waits for a rising edge in the new clock.
5. The new clock is now active.
6. The OSCSTAT register is updated as required.
7. Clock switch is complete.

See Figure 5-7 for more details.

If the internal oscillator speed is switched between two clocks of the same source, there is no start-up delay before the new frequency is selected. Clock switching time delays are shown in Table 5-1.

Start-up delay specifications are located in the oscillator tables of **Section 30.0 “Electrical Specifications”**.

6.0 REFERENCE CLOCK MODULE

The reference clock module provides the ability to send a divided clock to the clock output pin of the device (CLKR) and provide a secondary internal clock source to the modulator module. This module is available in all oscillator configurations and allows the user to select a greater range of clock submultiples to drive external devices in the application. The reference clock module includes the following features:

- System clock is the source
- Available in all oscillator configurations
- Programmable clock divider
- Output enable to a port pin
- Selectable duty cycle
- Slew rate control

The reference clock module is controlled by the CLKRCON register (Register 6-1) and is enabled when setting the CLKREN bit. To output the divided clock signal to the CLKR port pin, the CLKROE bit must be set. The CLKRDIV<2:0> bits enable the selection of 8 different clock divider options. The CLKRDC<1:0> bits can be used to modify the duty cycle of the output clock(1). The CLKRSLR bit controls slew rate limiting.

Note 1: If the base clock rate is selected without a divider, the output clock will always have a duty cycle equal to that of the source clock, unless a 0% duty cycle is selected. If the clock divider is set to base clock/2, then 25% and 75% duty cycle accuracy will be dependent upon the source clock.

For information on using the reference clock output with the modulator module, see **Section 23.0 “Data Signal Modulator”**.

6.1 Slew Rate

The slew rate limitation on the output port pin can be disabled. The slew rate limitation can be removed by clearing the CLKRSLR bit in the CLKRCON register.

6.2 Effects of a Reset

Upon any device Reset, the reference clock module is disabled. The user's firmware is responsible for initializing the module before enabling the output. The registers are reset to their default values.

6.3 Conflicts with the CLKR Pin

There are two cases when the reference clock output signal cannot be output to the CLKR pin, if:

- LP, XT or HS Oscillator mode is selected.
- CLKOUT function is enabled.

Even if either of these cases are true, the module can still be enabled and the reference clock signal may be used in conjunction with the modulator module.

6.3.1 OSCILLATOR MODES

If LP, XT or HS oscillator modes are selected, the OSC2/CLKR pin must be used as an oscillator input pin and the CLKR output cannot be enabled. See **Section 5.2 “Clock Source Types”** for more information on different oscillator modes.

6.3.2 CLKOUT FUNCTION

The CLKOUT function has a higher priority than the reference clock module. Therefore, if the CLKOUT function is enabled by the $\overline{\text{CLKOUTEN}}$ bit in Configuration Word 1, FOSC/4 will always be output on the port pin. Reference **Section 4.0 “Device Configuration”** for more information.

6.4 Operation During Sleep

As the reference clock module relies on the system clock as its source, and the system clock is disabled in Sleep, the module does not function in Sleep, even if an external clock source or the Timer1 clock source is configured as the system clock. The module outputs will remain in their current state until the device exits Sleep.

7.0 RESETS

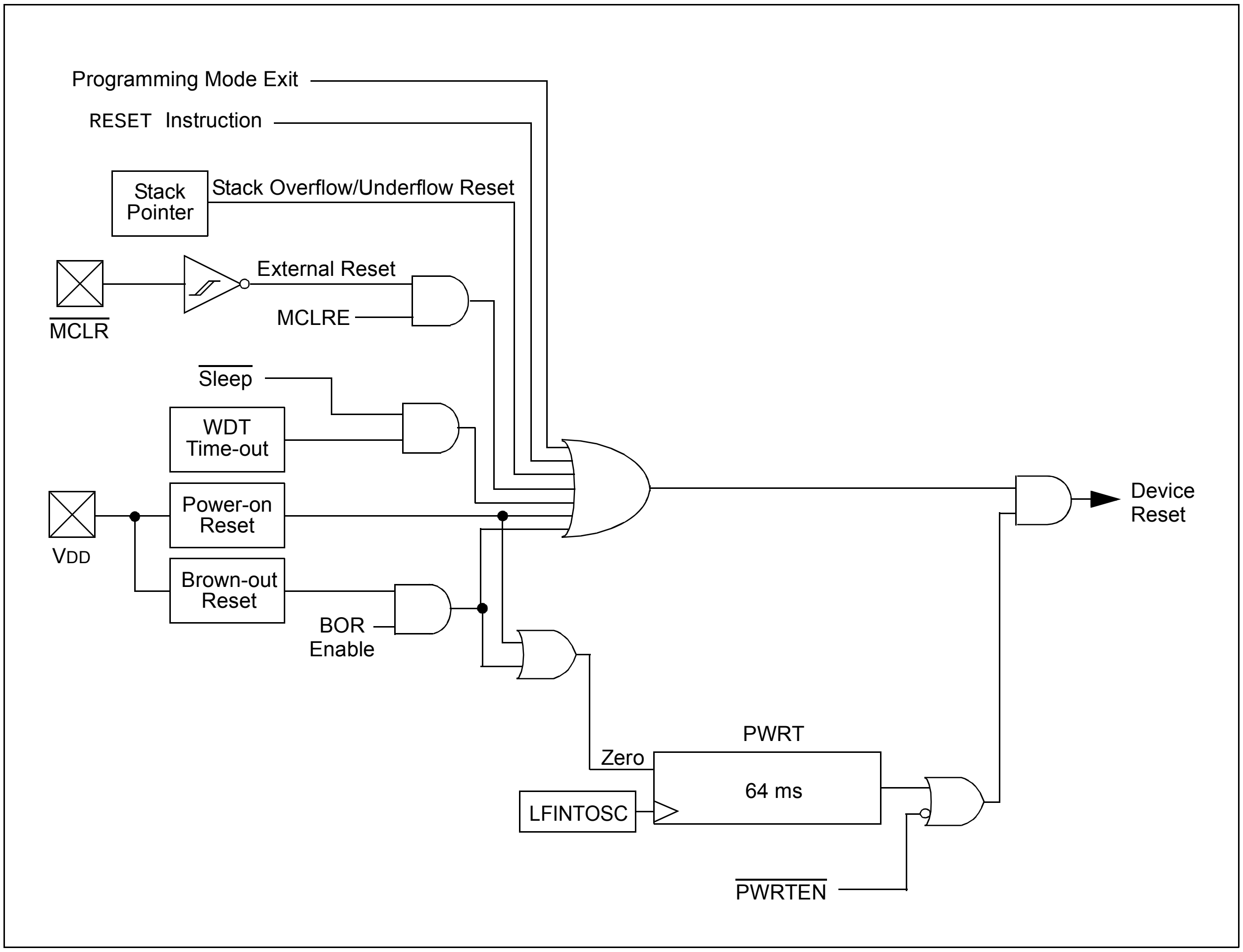
There are multiple ways to reset this device:

- Power-on Reset (POR)
- Brown-out Reset (BOR)
- $\overline{\text{MCLR}}$ Reset
- WDT Reset
- RESET instruction
- Stack Overflow
- Stack Underflow
- Programming mode exit

To allow VDD to stabilize, an optional power-up timer can be enabled to extend the Reset time after a BOR or POR event.

A simplified block diagram of the On-Chip Reset Circuit is shown in Figure 7-1.

FIGURE 7-1: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



9.0 POWER-DOWN MODE (SLEEP)

The Power-Down mode is entered by executing a `SLEEP` instruction.

Upon entering Sleep mode, the following conditions exist:

1. WDT will be cleared but keeps running, if enabled for operation during Sleep.
2. $\overline{\text{PD}}$ bit of the STATUS register is cleared.
3. $\overline{\text{TO}}$ bit of the STATUS register is set.
4. CPU clock is disabled.
5. 31 kHz LFINTOSC is unaffected and peripherals that operate from it may continue operation in Sleep.
6. Timer1 oscillator is unaffected and peripherals that operate from it may continue operation in Sleep.
7. ADC is unaffected, if the dedicated FRC clock is selected.
8. Capacitive Sensing oscillator is unaffected.
9. I/O ports maintain the status they had before `SLEEP` was executed (driving high, low or high-impedance).
10. Resets other than WDT are not affected by Sleep mode.

Refer to individual chapters for more details on peripheral operation during Sleep.

To minimize current consumption, the following conditions should be considered:

- I/O pins should not be floating
- External circuitry sinking current from I/O pins
- Internal circuitry sourcing current from I/O pins
- Current draw from pins with internal weak pull-ups
- Modules using 31 kHz LFINTOSC
- Modules using Timer1 oscillator

I/O pins that are high-impedance inputs should be pulled to V_{DD} or V_{SS} externally to avoid switching currents caused by floating inputs.

Examples of internal circuitry that might be sourcing current include modules such as the DAC and FVR modules. See **Section 17.0 "Digital-to-Analog Converter (DAC) Module"** and **Section 14.0 "Fixed Voltage Reference (FVR)"** for more information on these modules.

9.1 Wake-up from Sleep

The device can wake-up from Sleep through one of the following events:

1. External Reset input on $\overline{\text{MCLR}}$ pin, if enabled
2. BOR Reset, if enabled
3. POR Reset
4. Watchdog Timer, if enabled
5. Any external interrupt
6. Interrupts by peripherals capable of running during Sleep (see individual peripheral for more information)

The first three events will cause a device Reset. The last three events are considered a continuation of program execution. To determine whether a device Reset or wake-up event occurred, refer to **Section 7.10 "Determining the Cause of a Reset"**.

When the `SLEEP` instruction is being executed, the next instruction (PC + 1) is prefetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be enabled. Wake-up will occur regardless of the state of the GIE bit. If the GIE bit is disabled, the device continues execution at the instruction after the `SLEEP` instruction. If the GIE bit is enabled, the device executes the instruction after the `SLEEP` instruction, the device will then call the Interrupt Service Routine. In cases where the execution of the instruction following `SLEEP` is not desirable, the user should have a `NOP` after the `SLEEP` instruction.

The WDT is cleared when the device wakes up from Sleep, regardless of the source of wake-up.

10.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1 ms. See **Section 30.0 “Electrical Specifications”** for the LFINTOSC tolerances.

10.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word 1. See Table 10-1.

10.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word 1 are set to ‘`11`’, the WDT is always on.

WDT protection is active during Sleep.

10.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word 1 are set to ‘`10`’, the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

10.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word 1 are set to ‘`01`’, the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 10-1 for more details.

TABLE 10-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
`11`	X	X	Active
`10`	X	Awake	Active
		Sleep	Disabled
`01`	`1`	X	Active
	`0`		Disabled
`00`	X	X	Disabled

10.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is 2 seconds.

10.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- `CLRWDT` instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail event
- WDT is disabled
- Oscillator Start-up TImer (OST) is running

See Table 10-2 for more information.

10.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

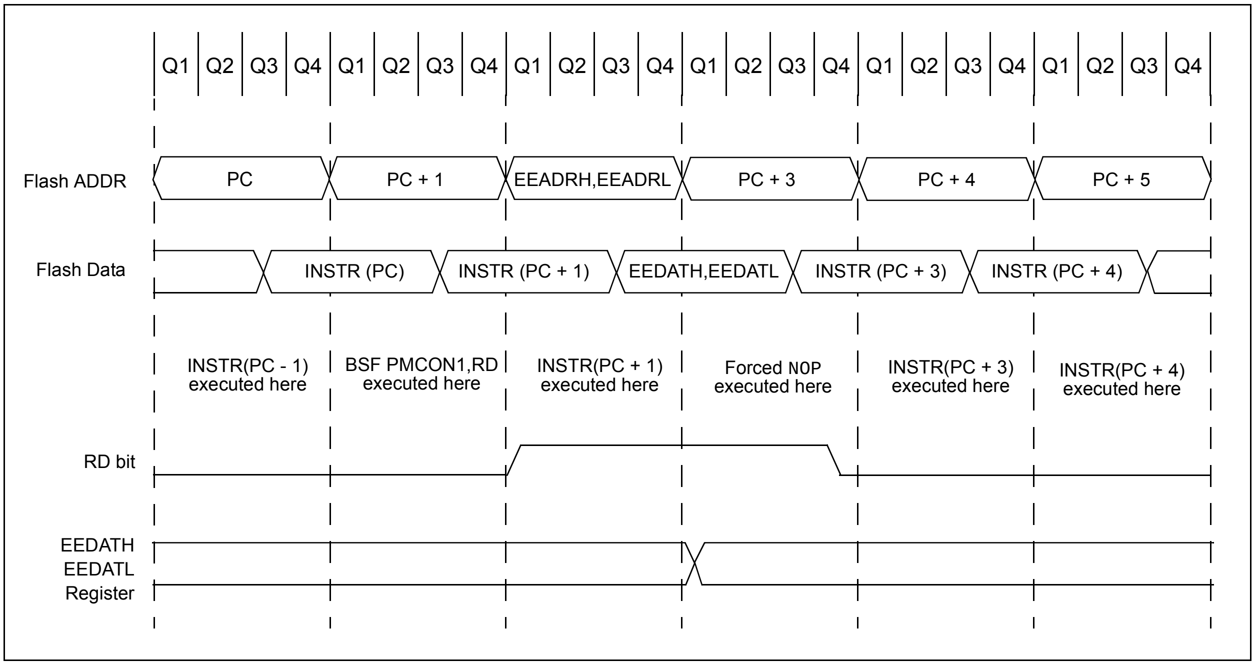
When the device exits Sleep, the WDT is cleared again. The WDT remains clear until the OST, if enabled, completes. See **Section 5.0 “Oscillator Module (With Fail-Safe Clock Monitor)”** for more information on the OST.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{\text{TO}}$ and $\overline{\text{PD}}$ bits in the STATUS register are changed to indicate the event. See **Register 3-1** for more information.

TABLE 10-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = `00`	Cleared
WDTE<1:0> = `01` and SWDTEN = `0`	
WDTE<1:0> = `10` and enter Sleep	
`CLRWDT` Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Exit Sleep + System Clock = XT, HS, LP	Cleared until the end of OST
Change INTOSC divider (IRCF bits)	Unaffected

FIGURE 11-1: FLASH PROGRAM MEMORY READ CYCLE EXECUTION



17.4 Low-Power Voltage State

In order for the DAC module to consume the least amount of power, one of the two voltage reference input sources to the resistor ladder must be disconnected. Either the positive voltage source, (VSOURCE+), or the negative voltage source, (VSOURCE-) can be disabled.

The negative voltage source is disabled by setting the DACLPS bit in the DACCON0 register. Clearing the DACLPS bit in the DACCON0 register disables the positive voltage source.

17.4.1 OUTPUT CLAMPED TO POSITIVE VOLTAGE SOURCE

The DAC output voltage can be set to VSOURCE+ with the least amount of power consumption by performing the following:

- Clearing the DACEN bit in the DACCON0 register.
- Setting the DACLPS bit in the DACCON0 register.
- Configuring the DACPSS bits to the proper positive source.
- Configuring the DACR<4:0> bits to ‘`11111`’ in the DACCON1 register.

This is also the method used to output the voltage level from the FVR to an output pin. See **Section 17.5 “Operation During Sleep”** for more information.

Reference Figure 17-3 for output clamping examples.

17.4.2 OUTPUT CLAMPED TO NEGATIVE VOLTAGE SOURCE

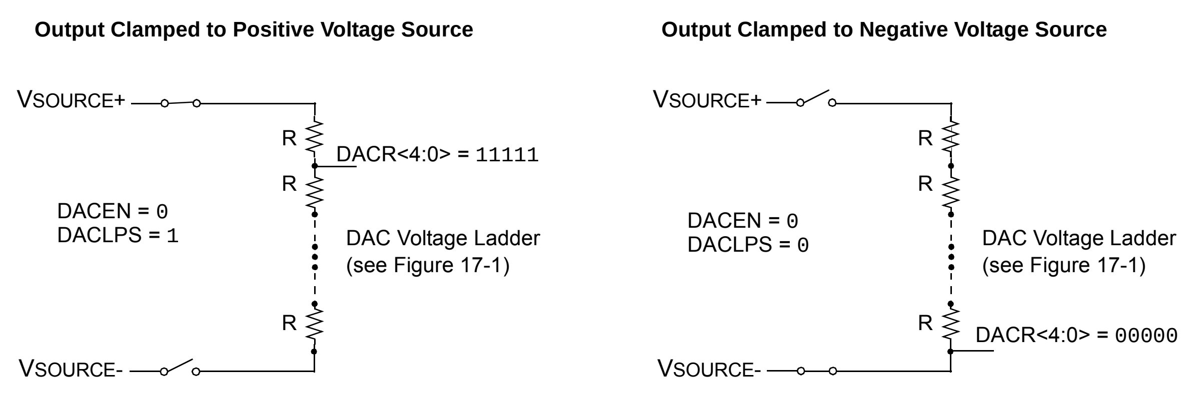
The DAC output voltage can be set to VSOURCE- with the least amount of power consumption by performing the following:

- Clearing the DACEN bit in the DACCON0 register.
- Clearing the DACLPS bit in the DACCON0 register.
- Configuring the DACNSS bits to the proper negative source.
- Configuring the DACR<4:0> bits to ‘`00000`’ in the DACCON1 register.

This allows the comparator to detect a zero-crossing while not consuming additional current through the DAC module.

Reference Figure 17-3 for output clamping examples.

FIGURE 17-3: OUTPUT VOLTAGE CLAMPING EXAMPLES



17.5 Operation During Sleep

When the device wakes up from Sleep through an interrupt or a Watchdog Timer time-out, the contents of the DACCON0 register are not affected. To minimize current consumption in Sleep mode, the voltage reference should be disabled.

17.6 Effects of a Reset

A device Reset affects the following:

- DAC is disabled.
- DAC output voltage is removed from the DACOUT pin.
- The DACR<4:0> range select bits are cleared.

TABLE 18-1: SRCLK FREQUENCY TABLE

SRCLK	Divider	Fosc = 32 MHz	Fosc = 20 MHz	Fosc = 16 MHz	Fosc = 4 MHz	Fosc = 1 MHz
`111`	512	62.5 kHz	39.0 kHz	31.3 kHz	7.81 kHz	1.95 kHz
`110`	256	125 kHz	78.1 kHz	62.5 kHz	15.6 kHz	3.90 kHz
`101`	128	250 kHz	156 kHz	125 kHz	31.25 kHz	7.81 kHz
`100`	64	500 kHz	313 kHz	250 kHz	62.5 kHz	15.6 kHz
`011`	32	1 MHz	625 kHz	500 kHz	125 kHz	31.3 kHz
`010`	16	2 MHz	1.25 MHz	1 MHz	250 kHz	62.5 kHz
`001`	8	4 MHz	2.5 MHz	2 MHz	500 kHz	125 kHz
`000`	4	8 MHz	5 MHz	4 MHz	1 MHz	250 kHz

REGISTER 18-1: SRCON0: SR LATCH CONTROL 0 REGISTER

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	R/S-0/0	R/S-0/0
SRLEN	SRCLK<2:0>			SRQEN	SRNQEN	SRPS	SRPR
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	S = Bit is set only

bit 7 **SRLEN:** SR Latch Enable bit
`1` = SR Latch is enabled
`0` = SR Latch is disabled

bit 6-4 **SRCLK<2:0>:** SR Latch Clock Divider bits
`000` = Generates a 1 FOSC wide pulse every 4th FOSC cycle clock
`001` = Generates a 1 FOSC wide pulse every 8th FOSC cycle clock
`010` = Generates a 1 FOSC wide pulse every 16th FOSC cycle clock
`011` = Generates a 1 FOSC wide pulse every 32nd FOSC cycle clock
`100` = Generates a 1 FOSC wide pulse every 64th FOSC cycle clock
`101` = Generates a 1 FOSC wide pulse every 128th FOSC cycle clock
`110` = Generates a 1 FOSC wide pulse every 256th FOSC cycle clock
`111` = Generates a 1 FOSC wide pulse every 512th FOSC cycle clock

bit 3 **SRQEN:** SR Latch Q Output Enable bit
If SRLEN = `1`:
`1` = Q is present on the SRQ pin
`0` = External Q output is disabled
If SRLEN = `0`:
SR Latch is disabled

bit 2 **SRNQEN:** SR Latch $\overline{Q}$ Output Enable bit
If SRLEN = `1`:
`1` = $\overline{Q}$ is present on the SRnQ pin
`0` = External $\overline{Q}$ output is disabled
If SRLEN = `0`:
SR Latch is disabled

bit 1 **SRPS:** Pulse Set Input of the SR Latch bit(1)
`1` = Pulse set input for 1 Q-clock period
`0` = No effect on set input.

bit 0 **SRPR:** Pulse Reset Input of the SR Latch bit(1)
`1` = Pulse reset input for 1 Q-clock period
`0` = No effect on reset input.

Note 1: Set only, always reads back ‘`0`’.

24.2 Compare Mode

The Compare mode function described in this section is available and identical for CCP modules ECCP1, ECCP2, CCP3 and CCP4.

Compare mode makes use of the 16-bit Timer1 resource. The 16-bit value of the CCPRxH:CCPRxL register pair is constantly compared against the 16-bit value of the TMR1H:TMR1L register pair. When a match occurs, one of the following events can occur:

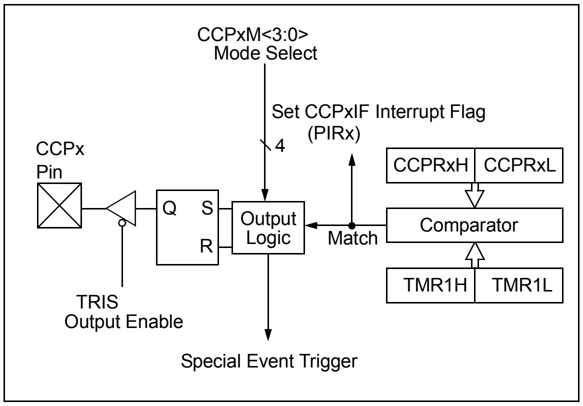
- Toggle the CCPx output
- Set the CCPx output
- Clear the CCPx output
- Generate a Special Event Trigger
- Generate a Software Interrupt

The action on the pin is based on the value of the CCPxM<3:0> control bits of the CCPxCON register. At the same time, the interrupt flag CCPxIF bit is set.

All Compare modes can generate an interrupt.

Figure 24-2 shows a simplified diagram of the Compare operation.

FIGURE 24-2: COMPARE MODE OPERATION BLOCK DIAGRAM



24.2.1 CCP PIN CONFIGURATION

The user must configure the CCPx pin as an output by clearing the associated TRIS bit.

Also, the CCPx pin function can be moved to alternative pins using the APFCON0 register. Refer to **Section 12.1 “Alternate Pin Function”** for more details.

Note: Clearing the CCPxCON register will force the CCPx compare output latch to the default low level. This is not the PORT I/O data latch.

24.2.2 TIMER1 MODE RESOURCE

In Compare mode, Timer1 must be running in either Timer mode or Synchronized Counter mode. The compare operation may not work in Asynchronous Counter mode.

See **Section 21.0 “Timer1 Module with Gate Control”** for more information on configuring Timer1.

Note: Clocking Timer1 from the system clock (FOSC) should not be used in Compare mode. In order for Compare mode to recognize the trigger event on the CCPx pin, TImer1 must be clocked from the instruction clock (FOSC/4) or from an external clock source.

24.2.3 SOFTWARE INTERRUPT MODE

When Generate Software Interrupt mode is chosen (CCPxM<3:0> = `1010`), the CCPx module does not assert control of the CCPx pin (see the CCPxCON register).

24.2.4 SPECIAL EVENT TRIGGER

When Special Event Trigger mode is chosen (CCPxM<3:0> = `1011`), the CCPx module does the following:

- Resets Timer1
- Starts an ADC conversion if ADC is enabled

The CCPx module does not assert control of the CCPx pin in this mode.

The Special Event Trigger output of the CCP occurs immediately upon a match between the TMR1H, TMR1L register pair and the CCPRxH, CCPRxL register pair. The TMR1H, TMR1L register pair is not reset until the next rising edge of the Timer1 clock. The Special Event Trigger output starts an A/D conversion (if the A/D module is enabled). This allows the CCPRxH, CCPRxL register pair to effectively provide a 16-bit programmable period register for Timer1.

TABLE 24-3: SPECIAL EVENT TRIGGER

Device	CCPx/ECCPx
PIC16(L)F1826	ECCP1
PIC16(L)F1827	CCP4

Refer to **Section 16.2.5 “Special Event Trigger”** for more information.

Note 1: The Special Event Trigger from the CCP module does not set interrupt flag bit TMR1IF of the PIR1 register.

2: Removing the match condition by changing the contents of the CCPRxH and CCPRxL register pair, between the clock edge that generates the Special Event Trigger and the clock edge that generates the Timer1 Reset, will preclude the Reset from occurring.

The I^2C interface supports the following modes and features:

- Master mode
- Slave mode
- Byte NACKing (Slave mode)
- Limited Multi-master support
- 7-bit and 10-bit addressing
- Start and Stop interrupts
- Interrupt masking
- Clock stretching
- Bus collision detection
- General call address matching
- Address masking
- Address Hold and Data Hold modes
- Selectable SDAx hold times

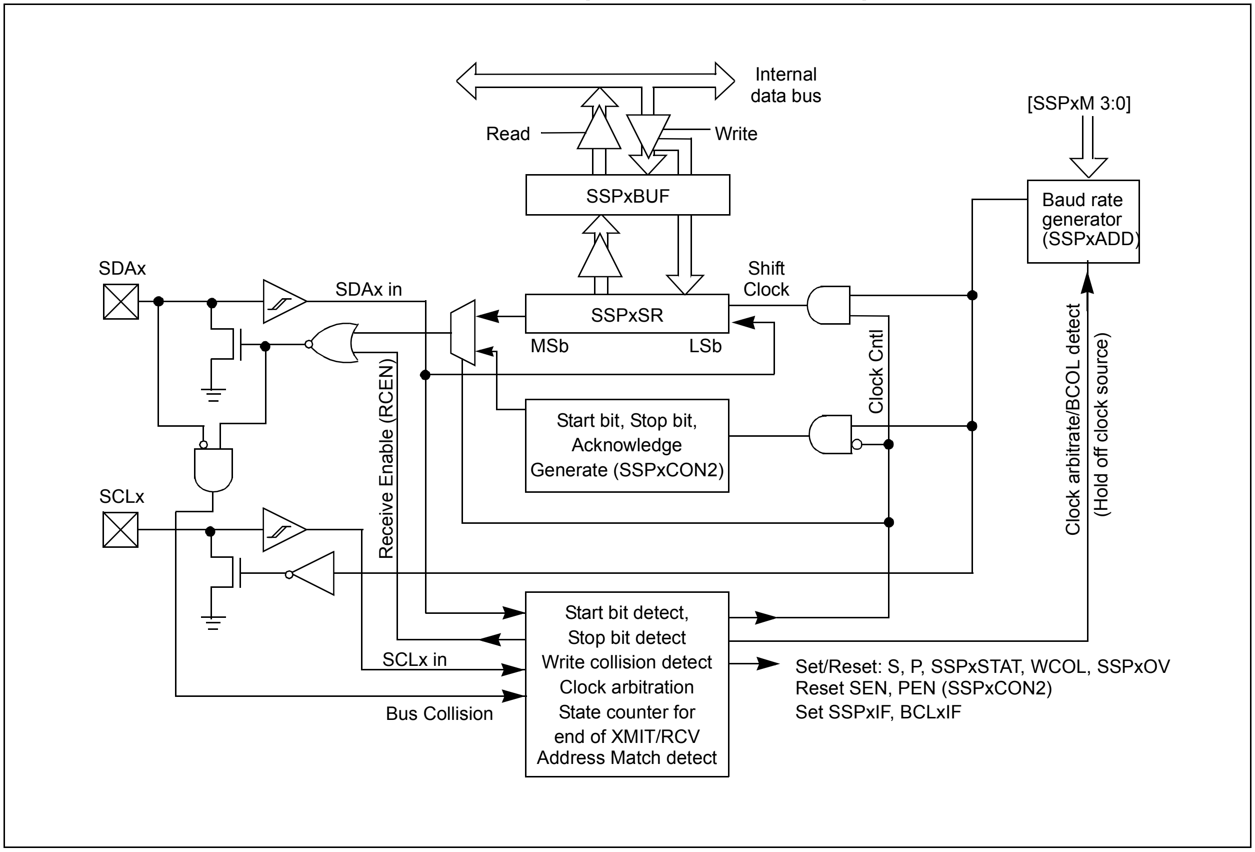
Figure 25-2 is a block diagram of the I^2C interface module in Master mode. Figure 25-3 is a diagram of the I^2C interface module in Slave mode.

The PIC16F1827 has two MSSP modules, MSSP1 and MSSP2, each module operating independently from the other.

Note 1: In devices with more than one MSSP module, it is very important to pay close attention to SSPxCONx register names. SSP1CON1 and SSP1CON2 registers control different operational aspects of the same module, while SSP1CON1 and SSP2CON1 control the same features for two different modules.

2: Throughout this section, generic references to an MSSP module in any of its operating modes may be interpreted as being equally applicable to MSSP1 or MSSP2. Register names, module I/O signals, and bit names may use the generic designator ‘x’ to indicate the use of a numeral to distinguish a particular module when required.

FIGURE 25-2: MSSPX BLOCK DIAGRAM (I^2C™ MASTER MODE)



25.2.6 SPI OPERATION IN SLEEP MODE

In SPI Master mode, module clocks may be operating at a different speed than when in full power mode; in the case of the Sleep mode, all clocks are halted.

Special care must be taken by the user when the MSSPx clock is much faster than the system clock.

In Slave mode, when MSSPx interrupts are enabled, after the master completes sending data, an MSSPx interrupt will wake the controller from Sleep.

If an exit from Sleep mode is not desired, MSSPx interrupts should be disabled.

In SPI Master mode, when the Sleep mode is selected, all module clocks are halted and the transmission/reception will remain in that state until the device wakes. After the device returns to Run mode, the module will resume transmitting and receiving data.

In SPI Slave mode, the SPI Transmit/Receive Shift register operates asynchronously to the device. This allows the device to be placed in Sleep mode and data to be shifted into the SPI Transmit/Receive Shift register. When all 8 bits have been received, the MSSPx interrupt flag bit will be set and if enabled, will wake the device.

TABLE 25-1: SUMMARY OF REGISTERS ASSOCIATED WITH SPI OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
APFCON0	RXDTSEL	SDO1SEL	SS1SEL	P2BSEL[1]	CCP2SEL[1]	P1DSEL	P1CSEL	CCP1SEL	119
ANSELA	—	—	—	ANSA4	ANSA3	ANSA2	ANSA1	ANSA0	123
ANSELB	ANSB7	ANSB6	ANSB5	ANSB4	ANSB3	ANSB2	ANSB1	—	128
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	86
PIE1	TMR1GIE	ADIE	RCIE	TXIE	SSP1IE	CCP1IE	TMR2IE	TMR1IE	87
PIR1	TMR1GIF	ADIF	RCIF	TXIF	SSP1IF	CCP1IF	TMR2IF	TMR1IF	91
SSPxBUF	Synchronous Serial Port Receive Buffer/Transmit Register								235*
SSPxCON1	WCOL	SSPxOV	SSPxEN	CKP	SSPxM3	SSPxM2	SSPxM1	SSPxM0	280
SSPxCON3	ACKTIM	PCIE	SCIE	BOEN	SDAHT	SBCDE	AHEN	DHEN	282
SSPxSTAT	SMP	CKE	D/$\overline{A}$	P	S	R/$\overline{W}$	UA	BF	279
TRISA	TRISA7	TRISA6	TRISA5	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	122
TRISB	TRISB7	TRISB6	TRISB5	TRISB4	TRISB3	TRISB2	TRISB1	TRISB0	127

Legend: — = Unimplemented location, read as ‘`0`’. Shaded cells are not used by the MSSPx in SPI mode.
* Page provides register information.

Note 1: PIC16(L)F1827 only.

When one device is transmitting a logical one, or letting the line float, and a second device is transmitting a logical zero, or holding the line low, the first device can detect that the line is not a logical one. This detection, when used on the SCLx line, is called clock stretching. Clock stretching gives slave devices a mechanism to control the flow of data. When this detection is used on the SDAx line, it is called arbitration. Arbitration ensures that there is only one master device communicating at any single time.

25.3.1 CLOCK STRETCHING

When a slave device has not completed processing data, it can delay the transfer of more data through the process of Clock Stretching. An addressed slave device may hold the SCLx clock line low after receiving or sending a bit, indicating that it is not yet ready to continue. The master that is communicating with the slave will attempt to raise the SCLx line in order to transfer the next bit, but will detect that the clock line has not yet been released. Because the SCLx connection is open-drain, the slave has the ability to hold that line low until it is ready to continue communicating.

Clock stretching allows receivers that cannot keep up with a transmitter to control the flow of incoming data.

25.3.2 ARBITRATION

Each master device must monitor the bus for Start and Stop bits. If the device detects that the bus is busy, it cannot begin a new message until the bus returns to an Idle state.

However, two master devices may try to initiate a transmission on or about the same time. When this occurs, the process of arbitration begins. Each transmitter checks the level of the SDAx data line and compares it to the level that it expects to find. The first transmitter to observe that the two levels don't match, loses arbitration, and must stop transmitting on the SDAx line.

For example, if one transmitter holds the SDAx line to a logical one (lets it float) and a second transmitter holds it to a logical zero (pulls it low), the result is that the SDAx line will be low. The first transmitter then observes that the level of the line is different than expected and concludes that another transmitter is communicating.

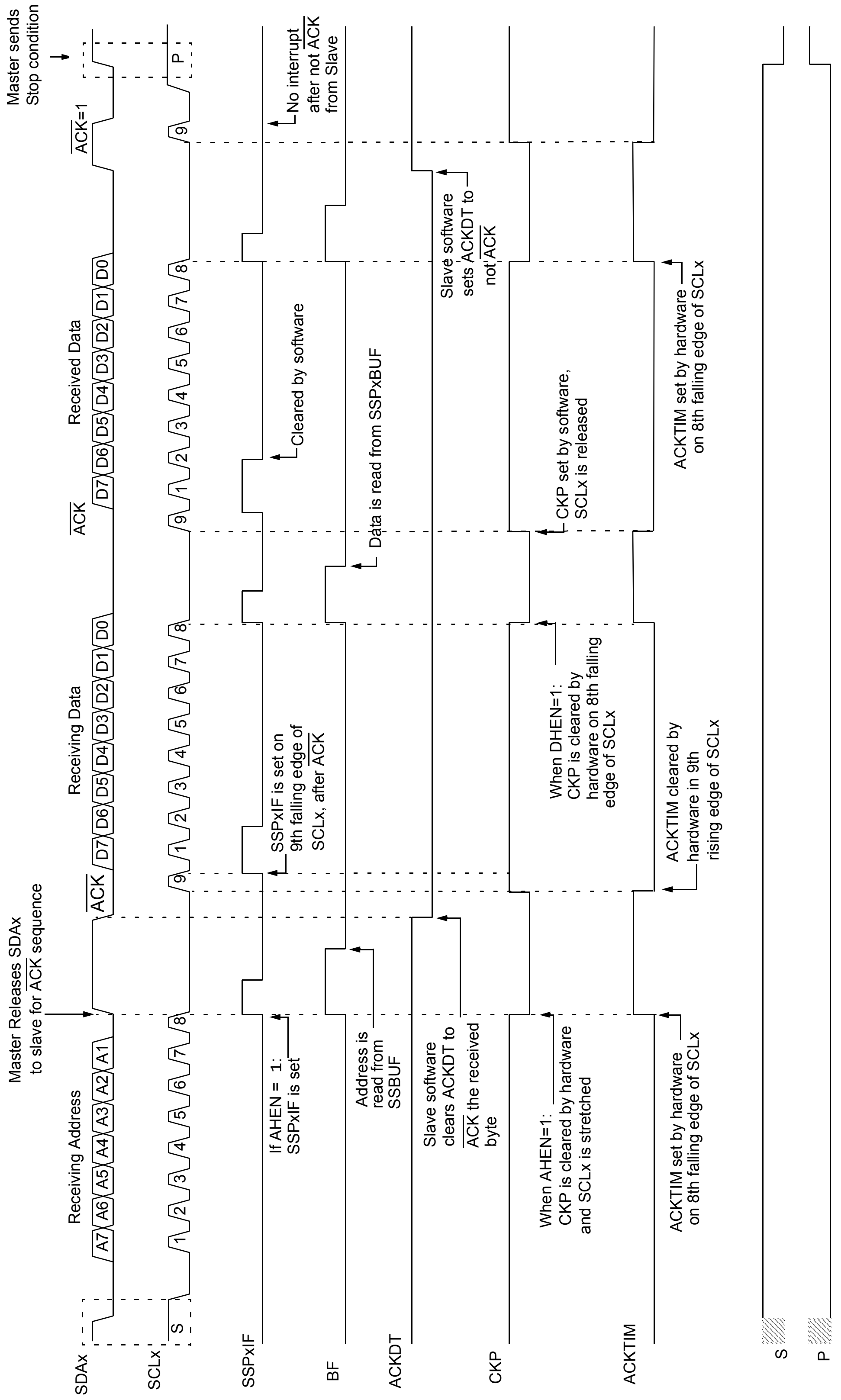
The first transmitter to notice this difference is the one that loses arbitration and must stop driving the SDAx line. If this transmitter is also a master device, it also must stop driving the SCLx line. It then can monitor the lines for a Stop condition before trying to reissue its transmission. In the meantime, the other device that has not noticed any difference between the expected and actual levels on the SDAx line continues with it's original transmission. It can do so without any complications, because so far, the transmission appears exactly as expected with no other transmitter disturbing the message.

Slave Transmit mode can also be arbitrated, when a master addresses multiple slaves, but this is less common.

If two master devices are sending a message to two different slave devices at the address stage, the master sending the lower slave address always wins arbitration. When two master devices send messages to the same slave address, and addresses can sometimes refer to multiple slaves, the arbitration process must continue into the data stage.

Arbitration usually occurs very rarely, but it is a necessary process for proper multi-master support.

FIGURE 25-16: I²C SLAVE, 7-BIT ADDRESS, RECEPTION (SEN = 0, AHEN = 1, DHEN = 1)



26.3.1 AUTO-BAUD DETECT

The EUSART module supports automatic detection and calibration of the baud rate.

In the Auto-Baud Detect (ABD) mode, the clock to the BRG is reversed. Rather than the BRG clocking the incoming RX signal, the RX signal is timing the BRG. The Baud Rate Generator is used to time the period of a received 55h (ASCII "U") which is the Sync character for the LIN bus. The unique feature of this character is that it has five rising edges including the Stop bit edge.

Setting the ABDEN bit of the BAUDCON register starts the auto-baud calibration sequence (Figure 26-6). While the ABD sequence takes place, the EUSART state machine is held in Idle. On the first rising edge of the receive line, after the Start bit, the SPBRG begins counting up using the BRG counter clock as shown in Table 26-6. The fifth rising edge will occur on the RX pin at the end of the eighth bit period. At that time, an accumulated value totaling the proper BRG period is left in the SPBRGH, SPBRGL register pair, the ABDEN bit is automatically cleared and the RCIF interrupt flag is set. The value in the RCREG needs to be read to clear the RCIF interrupt. RCREG content should be discarded. When calibrating for modes that do not use the SPBRGH register the user can verify that the SPBRGL register did not overflow by checking for 00h in the SPBRGH register.

The BRG auto-baud clock is determined by the BRG16 and BRGH bits as shown in Table 26-6. During ABD, both the SPBRGH and SPBRGL registers are used as a 16-bit counter, independent of the BRG16 bit setting. While calibrating the baud rate period, the SPBRGH and SPBRGL registers are clocked at 1/8th the BRG base clock rate. The resulting byte measurement is the average bit time when clocked at full speed.

Note 1: If the WUE bit is set with the ABDEN bit, auto-baud detection will occur on the byte following the Break character (see **Section 26.3.3 "Auto-Wake-up on Break"**).

2: It is up to the user to determine that the incoming character baud rate is within the range of the selected BRG clock source. Some combinations of oscillator frequency and EUSART baud rates are not possible.

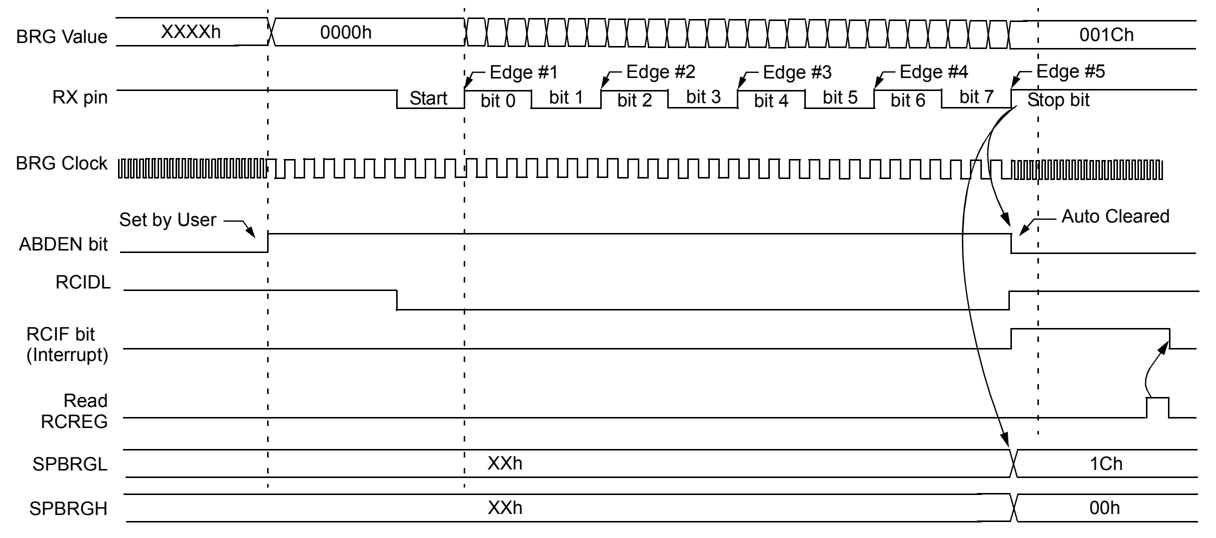
3: During the auto-baud process, the auto-baud counter starts counting at 1. Upon completion of the auto-baud sequence, to achieve maximum accuracy, subtract 1 from the SPBRGH:SPBRGL register pair.

TABLE 26-6: BRG COUNTER CLOCK RATES

BRG16	BRGH	BRG Base Clock	BRG ABD Clock
0	0	FOSC/64	FOSC/512
0	1	FOSC/16	FOSC/128
1	0	FOSC/16	FOSC/128
1	1	FOSC/4	FOSC/32

Note: During the ABD sequence, SPBRGL and SPBRGH registers are both used as a 16-bit counter, independent of BRG16 setting.

FIGURE 26-6: AUTOMATIC BAUD RATE CALIBRATION

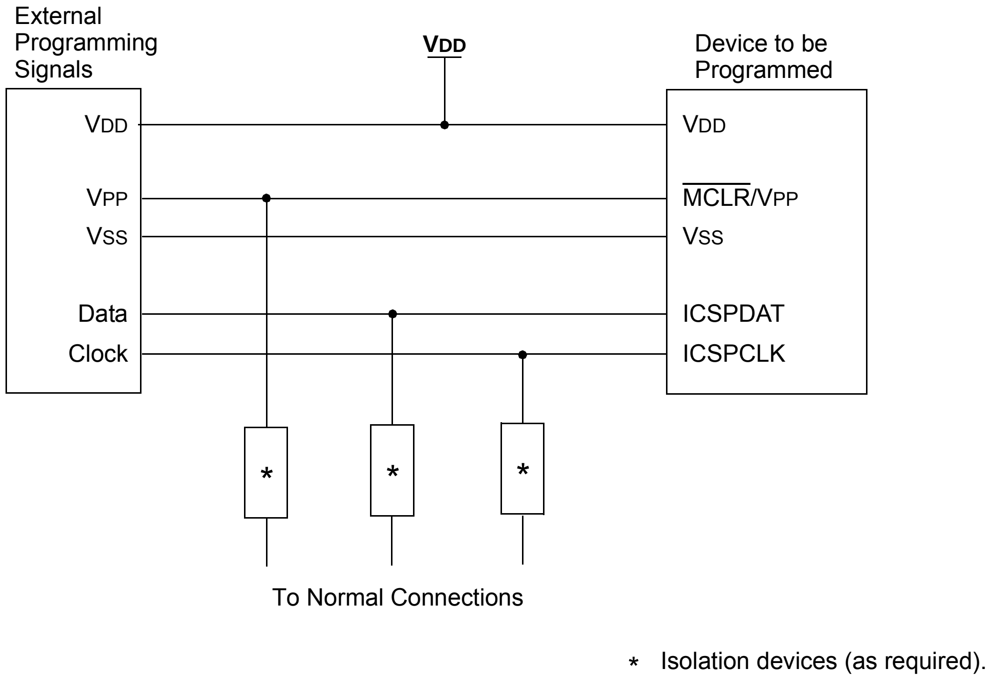


Note 1: The ABD sequence requires the **EUSART** module to be configured in Asynchronous mode.

For additional interface recommendations, refer to your specific device programmer manual prior to PCB design.

It is recommended that isolation devices be used to separate the programming pins from other circuitry. The type of isolation is highly dependent on the specific application and may include devices such as resistors, diodes, or even jumpers. See Figure 28-4 for more information.

FIGURE 28-4: TYPICAL CONNECTION FOR ICSP™ PROGRAMMING



NOTES:

30.2 DC Characteristics: PIC16(L)F1826/27-I/E (Industrial, Extended) (Continued)

PIC16LF1826/27			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
PIC16F1826/27			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40°C ≤ TA ≤ +85°C for industrial -40°C ≤ TA ≤ +125°C for extended				
Param No.	**Device Characteristics**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**	
						VDD	**Note**
	Supply Current (IDD)(1, 2)						
D019		—	4.0	7.3	mA	3.0	FOSC = 32 MHz HFINTOSC mode **(Note 3)**
		—	4.4	7.5	mA	3.6	
D019		—	4.2	7.3	mA	3.0	FOSC = 32 MHz HFINTOSC mode **(Note 3)**
		—	4.6	7.5	mA	5.0	
D020		—	4.0	6.0	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 4)**
		—	4.7	7.0	mA	3.6	
D020		—	4.2	6.8	mA	3.0	FOSC = 32 MHz HS Oscillator mode **(Note 4)**
		—	4.9	7.6	mA	5.0	
D021		—	410	0.65	mA	1.8	FOSC = 4 MHz EXTRC mode **(Note 5)**
		—	710	1.25	mA	3.0	
D021		—	430	0.695	mA	1.8	FOSC = 4 MHz EXTRC mode **(Note 5)**
		—	730	1.3	mA	3.0	
		—	860	1.35	mA	5.0	

* These parameters are characterized but not tested.

† Data in “Typ” column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: The test conditions for all IDD measurements in active operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins as inputs, pulled to VDD; $\overline{MCLR}$ = VDD; WDT disabled.

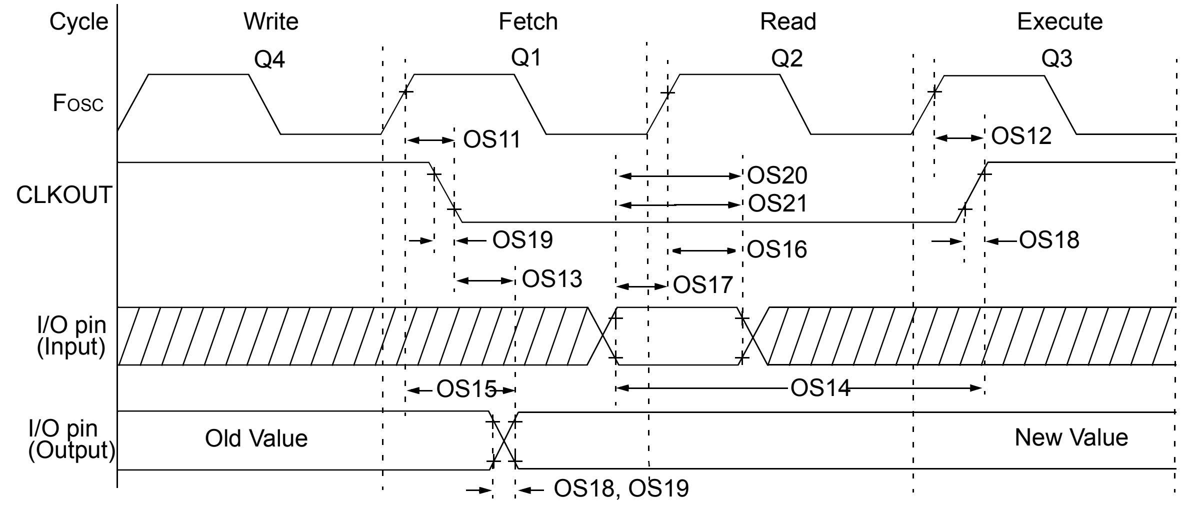
2: The supply current is mainly a function of the operating voltage and frequency. Other factors, such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature, also have an impact on the current consumption.

3: 8 MHz internal RC oscillator with 4x PLL enabled.

4: 8 MHz crystal oscillator with 4x PLL enabled.

5: For RC oscillator configurations, current through REXT is not included. The current through the resistor can be extended by the formula IR = VDD/2REXT (mA) with REXT in kΩ.

FIGURE 30-7: CLKOUT AND I/O TIMING

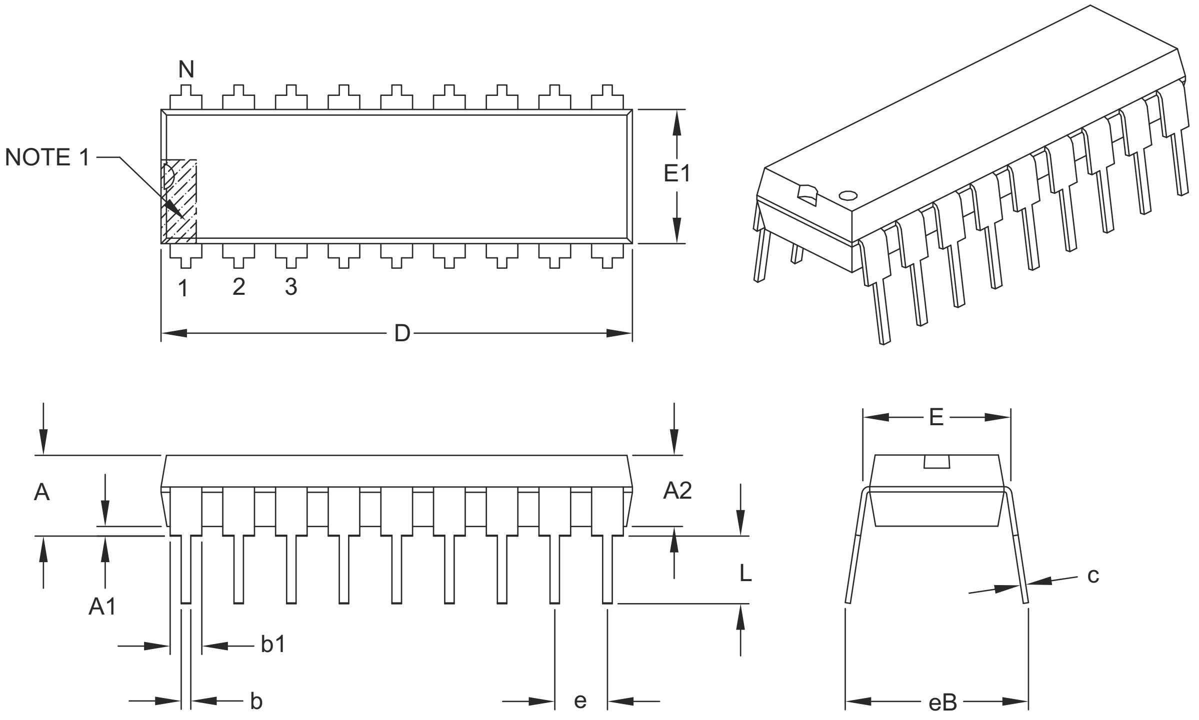


33.2 Package Details

The following sections give the technical details of the packages.

18-Lead Plastic Dual In-Line (P) – 300 mil Body [PDIP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES		
Dimension Limits		MIN	NOM	MAX
Number of Pins	N	18		
Pitch	e	.100 BSC		
Top to Seating Plane	A	–	–	.210
Molded Package Thickness	A2	.115	.130	.195
Base to Seating Plane	A1	.015	–	–
Shoulder to Shoulder Width	E	.300	.310	.325
Molded Package Width	E1	.240	.250	.280
Overall Length	D	.880	.900	.920
Tip to Seating Plane	L	.115	.130	.150
Lead Thickness	c	.008	.010	.014
Upper Lead Width	b1	.045	.060	.070
Lower Lead Width	b	.014	.018	.022
Overall Row Spacing §	eB	–	–	.430

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. § Significant Characteristic.
3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-007B